

Docket No.: WMP-IFT-699

*[Signature]*  
b-1002  
J1046 U.S. PRO  
10/073847  
02/11/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : MATTHIAS STECHER ET AL.

Filed : CONCURRENTLY HEREWITH

Title : SOI COMPONENT

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,  
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent 6,153,912 (Holst), dated November 28, 2000;

German Published Non-Prosecuted Patent Application DE 197 02 102 A1 (Fujihira et al.),  
dated July 24, 1997, semiconductor device and method for fabricating the semiconductor  
device;

European Patent Application 0 497 427 A2 (Merchant et al.), dated August 5, 1992.

If no translation of pertinent portions of any foreign language patents or publications  
mentioned above is included with the aforementioned copies of those applications, patents  
and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

WERNER H. STEMER  
REG. NO. 34,956

Date: February 11, 2002

Lerner and Greenberg, P.A.  
Post Office Box 2480  
Hollywood, FL 33022-2480  
Tel: (954) 925-1100  
Fax: (954) 925-1101

/kf